[Claim 1]

A resin plating method comprising:

an etching step in which an article comprising a resin material is used as an object to be treated and is subjected to etching using an acidic etching bath containing manganese;

a catalyst application step using palladium as a catalyst metal; and

an electroless plating step,

the method further comprising a step of maintaining the palladium concentration in the acidic etching bath at 100 mg/L or less,

wherein the step of maintaining the palladium concentration in the acidic etching bath at 100 mg/L or less is performed by one or more methods selected from the group consisting of:

a method for removing palladium adsorbed on a jig;

a method for reducing the palladium concentration in an etching bath by cathodic electrolysis; and

a method for reducing the palladium concentration by iodide addition to an etching bath,

wherein the method for removing palladium adsorbed on a jig is a method of immersing a jig in a palladium-removing treatment solution comprising an aqueous solution containing at least one compound selected from the group consisting of nitric acid, persulfates, hydrogen peroxide, and compounds having a stability constant with palladium of 2.0 or more.

[Claim 2]

The resin plating method according to claim 1, wherein the method for reducing the palladium concentration in an etching bath by cathodic electrolysis is a method of depositing palladium in an etching bath on a cathode as metallic palladium by electrolytic treatment.

[Claim 3]

The resin plating method according to claim 1, wherein the method for reducing the palladium concentration by iodide addition to an etching bath is a method comprising adding to an etching bath at least one iodide selected from the group

consisting of sodium iodide, potassium iodide, iodic acid, iodates, periodic acid, and periodates, and separating the formed precipitate.

[Claim 4]

A method for controlling a resin plating etching bath, comprising maintaining the palladium concentration in a manganese-containing acidic etching bath at 100 mg/L or less, wherein the step of maintaining the palladium concentration in the acidic etching bath at 100 mg/L or less is performed by one or more methods selected from the group consisting of:

a method for removing palladium adsorbed on a jig;

a method for reducing the palladium concentration in an etching bath by cathodic electrolysis; and

a method for reducing the palladium concentration by iodide addition to an etching bath,

wherein the method for removing palladium adsorbed on a jig is a method of immersing a jig in a palladium-removing treatment solution comprising an aqueous solution containing at least one compound selected from the group consisting of nitric acid, persulfates, hydrogen peroxide, and compounds having a stability constant with palladium of 2.0 or more.

[Claim 5]

The method for controlling a resin plating etching bath according to claim 4, wherein the method for reducing the palladium concentration in an etching bath by cathodic electrolysis is a method of depositing palladium in an etching bath on a cathode as metallic palladium by electrolytic treatment.

[Claim 6]

The method for controlling a resin plating etching bath according to claim 4, wherein the method for reducing the palladium concentration by iodide addition to an etching bath is a method comprising adding to an etching bath at least one iodide selected from the group consisting of sodium iodide, potassium iodide, iodic acid, iodates, periodic acid, and periodates, and separating the formed precipitate.